

BIDIRECTIONAL TVS DIODE ARRAY

APPLICATIONS

- ◆ Cell Phone Handsets and Accessories
- ◆ Microprocessor based equipment
- ◆ Personal Digital Assistants (PDA's)
- ◆ Notebooks, Desktops, and Servers
- ◆ Portable Instrumentation
- ◆ Peripherals
- ◆ Pagers

IEC COMPATIBILITY

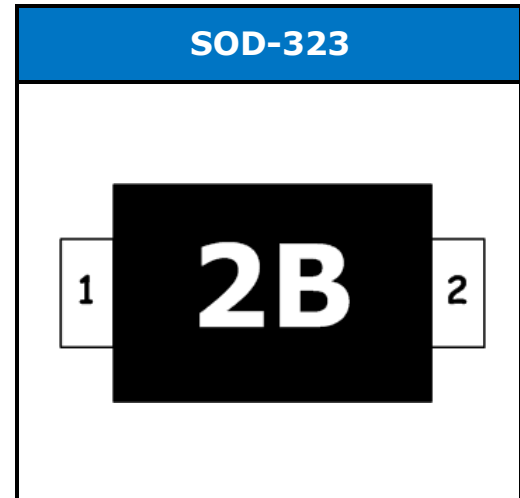
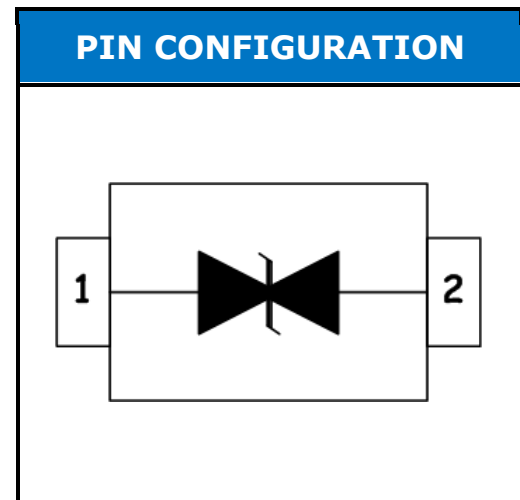
- ◆ IEC61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)
- ◆ IEC61000-4-5 (Lightning) 21A (8/20 μ s)

FEATURES

- ◆ 320 Watts Peak Pulse Power per Line ($t_p=8/20\mu$ s)
- ◆ Protects one I/O or power line
- ◆ Low clamping voltage
- ◆ Working voltages: 3V, 5V, 12V, 15V, 18V, 24V and 36V
- ◆ Low leakage current

MECHANICAL CHARACTERISTICS

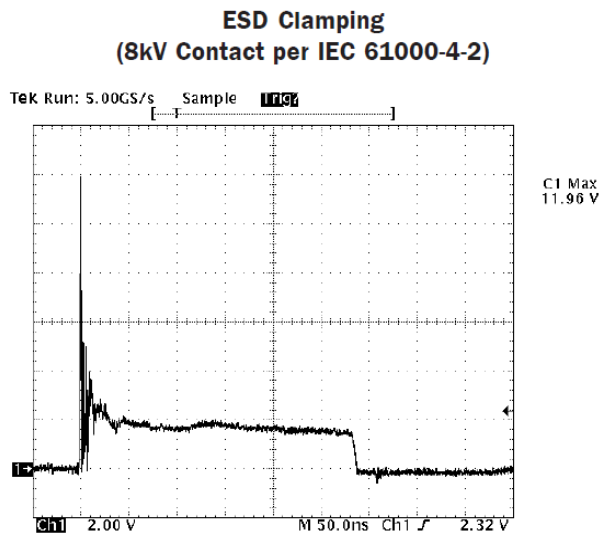
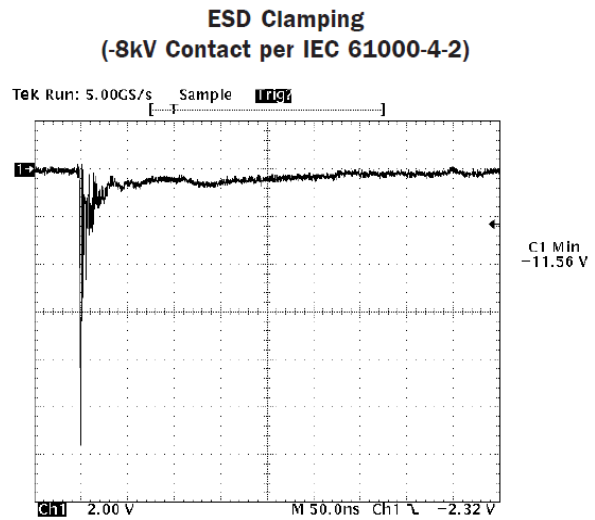
- ◆ JEDEC SOD-323 Package
- ◆ Molding Compound Flammability Rating : UL 94V-O
- ◆ Weight 5 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free



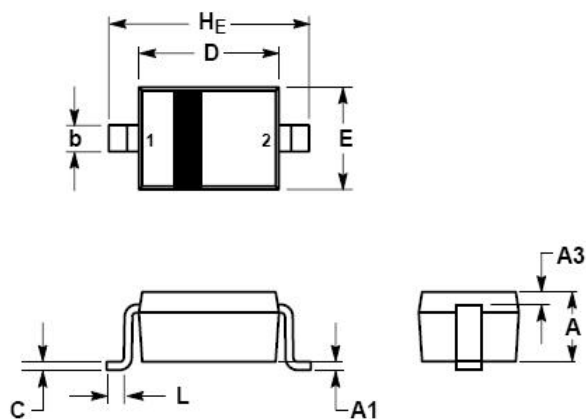
DEVICE CHARACTERISTICS

MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	320	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _C @1A (max.)	V _C (max.) (@A)		I _R (μA) (max.)	C _T (pF) (max.)
TESD03FB	2A	3	4	1	7.5	10.5	20	40	450
TESD05FB	2B	5	6	1	9.8	18	17	10	200
TESD12FB	2D	12	13.3	1	19	35	12	1	100
TESD15FB	2J	15	16.7	1	24	40	10	1	75
TESD18FB	2K	18	20.0	1	29	45	9	1	57
TESD24FB	2H	24	26.7	1	40	52	7	1	50
TESD36FB	2N	36	40	1	65	75	5	1	40



SOD-323 PACKAGE OUTLINE & DIMENSIONS



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

* SOLDERING FOOTPRINT

